

Appl. No. 10/611,480
Amdt. dated June 21, 2006
Reply to Office action of Feb. 22, 2006

Remarks/Arguments

Applicants thank Examiner Arbes for his careful examination of this application and for allowing claims 17-20. In response to the Office Action of February 22, 2006, applicants amend this application as follows:

1. The title of this application is changed to -- Wirebonder to Bond an IC Chip to a Substrate.
2. Claims 1-16 are canceled from this examination.

Applicants respectfully submit that as amended, this application is in allowable form.

Respectfully submitted,
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